

Title (en)

METHOD AND COMPOSITION FOR ELECTRO-CHEMICAL-MECHANICAL POLISHING

Title (de)

VERFAHREN UND ZUSAMMENSETZUNG FÜR ELEKTROCHEMISCHES-MECHANISCHES POLIEREN

Title (fr)

METHODES ET COMPOSITIONS POUR UN POLISSAGE ELECTRO-CHIMICO-MECANIQUE

Publication

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Application

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Abstract (en)

[origin: US2006163083A1] Methods and compositions for electro-chemical-mechanical polishing (e-CMP) of silicon chip interconnect materials, such as copper, are provided. The methods include the use of compositions according to the invention in combination with pads having various configurations.

IPC 8 full level

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